Schottky Barrier Diode

DB2X20600L

Panasonic

DB2X20600L

Silicon epitaxial planar type

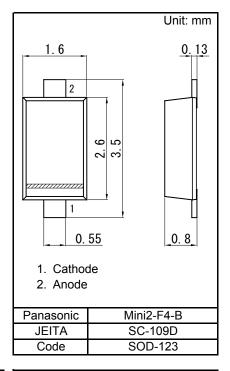
For high frequency rectification DB3X206K in Mini2 type package

■ Features

- · Low forward voltage VF
- Small reverse leakage current
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: D3

■ Packaging

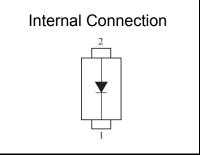
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	20	V
Repetitive peak reverse voltage	VRRM	20	V
Forward current (Average) *1	IF(AV)	1	Α
Non-repetitive peak forward surge current *2	IFSM	3	Α
Junction temperature	Tj	125	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +125	°C

Note: *1 For embedded alumina substrate



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^{*2 50} Hz sine wave 1 cycle (Non-repetitive peak current)

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■ Electrical Characteristics Ta = 25 °C ± 3 °C

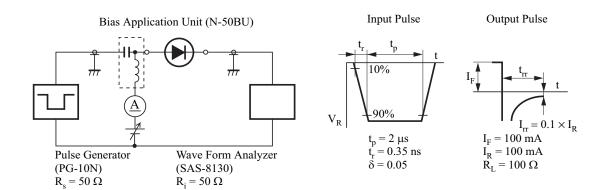
Symbol	Conditions	Min	Тур	Max	Unit
VF	IF = 1.0 A			0.45	V
IR	VR = 20 V			100	μA
Ct	VR = 10 V, f = 1 MHz		20		pF
trr	·		6		ns
	VF IR Ct	VF	VF	VF	VF IF = 1.0 A 0.45 IR VR = 20 V 100 Ct VR = 10 V, f = 1 MHz 20 trr IF = IR = 100 mA, 6

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. *1 trr test circuit

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: 2013-04-26

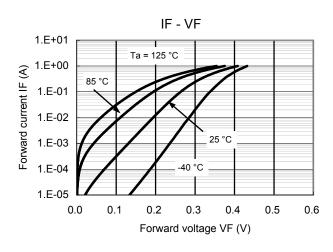


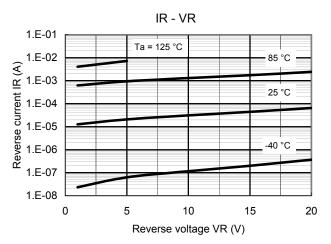
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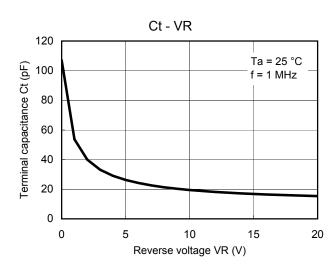
Schottky Barrier Diode

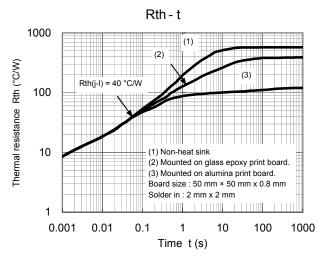
DB2X20600L

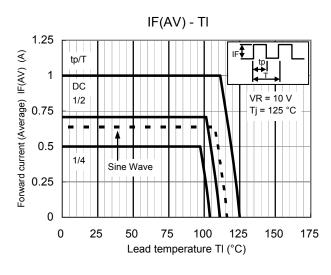
Technical Data (reference)

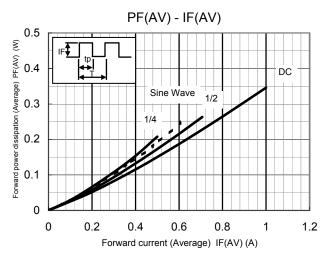












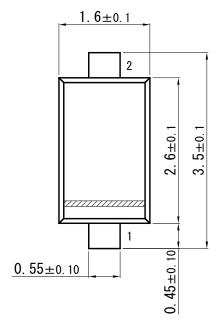
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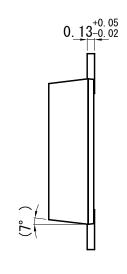
Schottky Barrier Diode

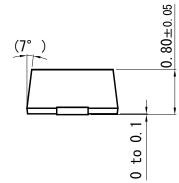
DB2X20600L

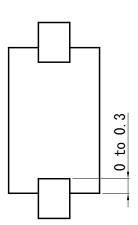
Mini2-F4-B

Unit: mm

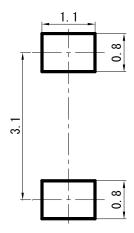








■ Land Pattern (Reference) (Unit: mm)



Established: 2010-06-10 Revised: 2013-04-26

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